

DETAILED ACTION

Response to Amendment

This Office Action is in response to the amendment filed August 18, 2004.

Accordingly, claims 86, 87 and 100 were amended.

Currently, claims 86, 87, 100 and 206-225 are pending in the application.

Examiner's Amendment

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with David Salzman on November 10, 2004.

The application has been amended as follows:

In the Claims:

Re claim 100, line 10, after "second", delete "planar", and line 11, after "second", delete "planar".

Allowable Subject Matter

Claims 86, 87, 100 and 206-225 are allowed.

The following is an examiner's statement of reasons for allowance: none of the prior art of record, taken alone or in combination, fairly shows or suggests all the process limitations as claimed.

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Re claim 86, none of the prior art of record discloses the steps of: locating a first subset of said electronic devices and a plurality of half-capacitors on a first semiconductor chip; locating a second subset of said electronic devices and a plurality of half-capacitors on a second semiconductor chip; and, aligning and affixing said first and second chips so as to capacitively couple said first and second chips using at least some of the half-capacitors on each of said chips.

Re claim 100, none of the prior art of record discloses the steps of: affixing said first chip to a substrate; aligning said second chip to said first chip; and, affixing said second chip to said substrate, thereby capacitively coupling corresponding half-capacitors on said first and second chips and providing direct capacitive coupling between said first and second chips.

Re claim 206, none of the prior art of record discloses the steps of: providing a plurality of first dice, said first dice each having half-capacitors formed on a surface thereof; providing a plurality of second dice, said second dice each having half-capacitors formed on a surface thereof; and arranging said dice overlaps at least three of said second dice, and each of said second dice overlaps at least three of said first first dice so that each of said first dice, thereby defining overlap areas, wherein at least some half-capacitors of said plurality of first dice are configured to be capacitively coupled to corresponding half-capacitors of said second dice in said overlap areas.

Re claim 214, none of the prior art of record discloses the steps of: providing a plurality of first dice, said first dice each having first half-capacitors formed on a surface thereof; providing a plurality of second dice, said second dice each having second half-capacitors formed on a surface thereof; and arranging said first dice so that each first die overlaps at least two of said second dice, thereby defining overlap areas, wherein said first half-capacitors located in said

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overlap areas are configured to be capacitively coupled to some of said second half-capacitors, wherein said first dice or said second dice have raised areas relative to said surfaces, the raised areas of each of said first or said second die contacting an area on one of the overlapping die.

Re claim 220, none of the prior art of record discloses the steps of: providing a plurality of first dice, said first dice each having half-capacitors formed on a surface thereof; providing a plurality of second dice, said second dice each having half-capacitors formed on a surface thereof; arranging said first dice so that each first die overlaps at least four of said second dice, thereby defining overlap areas; and aligning said first dice so that half-capacitors thereof located in said overlap areas are configured to be capacitively coupled to some half-capacitors of said second dice.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khanh Duong whose telephone number is (571) 272-1836. The examiner can normally be reached on Monday - Thursday (9:00 AM - 6:00 PM).

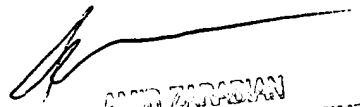
If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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KBD



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